Syllabus – Microelectronics Manufacturing and the Environment

Ara Philipossian

Department of Chemical & Environmental Engineering

CHEE, MSE & ECE 415 & 515

© 2017

Course Description

- This course will focus on the presentation of <u>basic</u> <u>semiconductor fabrication unit operations</u> as they relate to:
 - Theory of operation
 - Materials
 - Equipment
 - Fabrication processes
 - Key environmental impacts and challenges
- Prerequisites:
 - None

Instructor Information

- Instructor:
 - Name: Ara Philipossian
 - Office: Electrical & Computer Engineering Building, Room 223
 - Phone: 520 621 6101
 - E-Mail: <u>ara@engr.arizona.edu</u>

- Office Hours:
 - TBD
 - There will be no TA for this course
 - Other times by appointment only (send me an e-mail please)
 - Office hours are subject to change

Method of Instruction

- Class location: TBD Class meets once a week for 2½ hours with an additional 10 minute break in between.
- Course will be delivered in the form of traditional lectures as well as instructional videos:
 - Prof. Ara Philipossian UA Lectures
 Prof. Farhang Shadman UA Video
 Dr. Michael Goldstein Intel Video
 Prof. Srini Raghavan UA Video
 Dr. Robert Meagley Intel Video
 Dr. Larry Larsen Sematech Video
- <u>Self-discipline will be paramount</u> in order to keep up with the pace and the volume (and format) of information delivered.

Method of Instruction (continued)

- Homework:
 - Twenty or so assignments
- Exams:
 - Mid-Term No. 1
 - Mid-Term No. 2
- Group Project Proposal (Written and Oral):
 - Please see the next 5 slides

Project Proposal

ORAL PRESENTATION AND SUBMISSION DEADLINE

- Due date: TBD
- Deliver a hardcopy to Ara Philipossian in the class
- Present to the entire class (no more than 10 minutes and 9 PPT slides)

WRITTEN PROPOSAL LENGTH

- No more than 14 pages including figures and list of references
- Keep it crisp and to the point
- Font size: 11
- Spacing: Double
- MAXIMUM OF 5 STUDENTS PER GROUP

• FOCUS AREAS

- Process consumables replacement
- Process consumables reduction
- Process consumables re-use

TOPICS TO CHOSE FROM

- Electroplating of copper
- CMP of copper or dielectrics
- CMP of Shallow Trench Isolation
- Thermal oxidation
- LPCVD of dielectrics
- LPCVD of tungsten
- Wet cleaning and surface preparation
- Dry cleaning & surface preparation
- Rinsing
- Drying
- Post-CMP cleaning

• TOPICS TO CHOSE FROM (CONTINUED)

- Wet etching of silicon nitride or silicon dioxide
- Dry etching of silicon dioxide
- PVD of copper
- Plasma etching
- Lithography

• **RESEARCH OBJECTIVE**

- What problem are you solving?
- What opportunities are you suggesting to be exploited?
- What technology or usage issues motivate this problem?
- What has been done in this area in the past?
- How does your proposed work differ from what's already been done by other researchers?
- What is your research hypothesis?
- How will you verify that hypothesis?
- What is the potential impact on industry practice if the hypothesis is verified?

• RELATIONSHIP TO OTHER RESEARCH OR PRATICE

- What similar research to this proposal is being conducted by other universities?
- How does this proposal differ from that research

RESEARCH POTENTIAL IMPACT

- What concrete results are expected?
- How could those results be put into practice?
- How could an IC manufacturer benefit from the completion of this work?
- What technological advances must happen for that benefit to be realized?

• RESEARCH PLAN (ASSUME A 2-YEAR DURATION)

- Deliverables
- Timeline
- Technical tradeoffs that may have to be made
- Risks in this research and how they will be managed

• BIBLIOGRAPHY

- Roughly 10 publications relating to state-of-the-art and your proposed work
- Attach hardcopies of <u>all</u> referenced publications and submit it with your report (note that these pages are in addition to the 14 pages containing your report)

GRADING

- Your grade will be based on the following:
 - Creativity
 - Originality
 - Aesthetics & professionalism of the report
 - Impact to industry
 - Completeness & relevance of previous work cited in the bibliography and your ability to structure your proposal recognizing what's been done before by other researchers
 - Likelihood of success of your proposal

YOUR Final Grade

 Homework ZERO – I will not be collecting or grading any of the HWs I will post all solutions on D2L <u>Exams will be based on HW</u>

- Mid-Term Exam 1 30%
- Mid-Term Exam 2 40%
- Proposal 30%

Books

• Required Textbook:

- Microchip Manufacturing by S. Wolf, Lattice Press (2004).

- Recommended Books:
 - <u>Microchip Fabrication: A Practical Guide to Semiconductor</u>
 <u>Processing</u>, 4th Edition, by Peter Van Zant, McGraw-Hill Publishers (2000).
 - <u>VLSI Fabrication Principles: Silicon and Gallium Arsenide</u>, by Sorab K.
 Ghandhi, John Wiley (1994)
 - <u>Handbook of Semiconductor Wafer Cleaning Technology</u>, by Werner Kern, Noyes Publications (1993)
 - <u>Chemical Mechanical Planarization of Microelectronic Materials</u>, by Steigerwald, Murarka & Gutmann, John Wiley & Sons (1997).
 - Process Engineering Analysis in Semiconductor Device Fabrication, by Middleman and Hochberg, McGraw-Hill Publishers (1993).

Groundrules

- There will be no make-up exams whatsoever
- Turn off all mobile devices in the classroom
- Lectures start promptly
 - Please be on time
 - Students arriving more than 5 minutes late are requested to wait outside the classroom. Late students will be admitted into the classroom when there is a natural break in the lecture.
 - Being 5 minutes late means:
 - (5 minutes) x (29 students + 1 instructor)
 - 2¹/₂ hours of other people's time wasted
 - If you miss a lecture, please do not ask me for a tutorial on the subjects covered during the lecture
- Complete your reading assignment <u>prior</u> to each lecture

Groundrules (continued)

- Please do not seek the instructors' help in solving homework problems if you have not given the problem your best shot.
- You need to kindly show the instructor in writing your logic and deductive reasoning in attempting to solve a problem before the instructor proceeds to help you

Course Structure – Subject to Change

- Lecture <u>No. 1</u> by Ara Philipossian
 - Review of the Syllabus
 - Introduction to Device Fabrication
 - Introduction to Design for the Environment
 - Silicon Wafer Manufacturing Part 1
 - Silicon Wafer Manufacturing Part 2 (Please watch the video on D2L ASAP)
- Lecture <u>No. 2</u> by Ara Philipossian
 - Impurity Diffusion
 - Thermal Oxidation

Course Structure

- Lecture <u>No. 3</u> by Ara Philipossian
 - Thermal oxidation (continued)
 - Dielectric Deposition
- Lecture <u>No. 4</u> by Ara Philipossian, Srini Raghavan and Larry Larsen
 - Low k Dielectrics
 - <u>Ion Implantation (by Larry Larson Please watch the video on D2L</u> <u>ASAP)</u>
 - You need to download SRIM in order to solve the Implantation HW problems.
- Review Lectures (Nos. 5 and 6) by Ara Philipossian

Mid-Term Exam 1 ... Date TBD (duration = 2¹/₂ hours)

Course Structure

- Lecture <u>No. 7</u> by Ara Philipossian
 - Wet Etching, Cleaning and Surface Preparation
 - Drying (by Srini Raghavan Please watch video on D2L ASAP)
- Lectures <u>No. 8 and 9 by Ara Philipossian</u>
 - Chemical Mechanical Planarization (Parts I and II)
- Lecture <u>No. 10</u> by Ara Philipossian, Farhang Shadman, Michael Goldstein and Robert Meagley – Watch litho and metallization videos on D2L.
 - Lecture on the elements of the final proposal plus Q & A
 - Ultra-Pure Water Production, Use and Re-Use
 - Rinsing
 - Photolithography
 - Metallization

Course Structure

- Review Lecture (No. 11) by Ara Philipossian
- Proposal Presentations (written proposal due today in class)!

Mid-Term Exam 2 ... **Date TBD (duration = 2\frac{1}{2} hours)**